Chip Design Marketing and Lead Generation Programs Connect You with Real Buyers in the Advanced IC Design Market

Chip Design, www.chipdesignmag.com and Chip Design email newsletters reach over 100,000 design engineers and engineering managers working on advanced SoC designs.

Chip Design’s readers and www.chipdesignmag.com visitors are chip, programmable logic device and IP-related architects, designers, and testers. The readership also includes software protocol-application engineers and technical program managers. These architect-design-test engineers and managers are responsible for creating the latest generations of ASICs, structured ASIC, ASSPs, FPGAs, memory cores and SoC devices.

### Circulation

<table>
<thead>
<tr>
<th>Average Monthly Visitors on <a href="http://www.chipdesignmag.com">www.chipdesignmag.com</a></th>
<th>Magazine Readership</th>
<th>Email Newsletters Readership</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Page Views:</strong> 237,598&lt;br&gt;<strong>Visits:</strong> 42,053&lt;br&gt;<strong>Average Time on Site:</strong> 48:31</td>
<td>Chip Design Magazine is distributed to over 40,000 qualified design engineers and engineering managers working on advanced SoC designs</td>
<td>&gt; Chip Designer is distributed to 32,011 subscribers&lt;br&gt;IP Designer &amp; Integrator is distributed to 28,214 subscribers&lt;br&gt;FPGA &amp; PLD E-Product Alert is distributed to 44,018 subscribers&lt;br&gt;RF &amp; Microwave Systems is distributed to 27,018 subscribers</td>
</tr>
</tbody>
</table>

#### Powerful Purchasing Influence

System architect, design and test engineers and engineering managers working on advanced SoC designs—Chip Design readers—account for a third of all design engineers. These key enablers influence the purchase of nearly 80% of the total EDA market—or about $4 billion.

### Circulation Breakdown by Purchasing Responsibility

- **94.8%**: Specify/Authorize Influence the purchase of Design Automation tools and software
- **80.6%**: Specify/Authorize Influence the purchase of ASICs, FPGAs and PLDs
- **70.1%**: Specify/Authorize Influence the purchase of Intellectual Property
- **52.9%**: Specify/Authorize Influence the purchase of Standard IC Services
- **57.2%**: Specify/Authorize Influence the purchase of Test Equipment/Development Tools
- **35.6%**: Influence, specify or authorize the purchasing at companies with revenues of over $500 million.

### Top 30 Subscribing Companies

- **Altera**
- **AMD**
- **Analog Devices**
- **Atmel**
- **Broadcom**
- **Cisco**
- **Cypress Semiconductor**
- **Freescale**
- **Fujitsu**
- **GLOBALFOUNDRIES**
- **Hewlett-Packard**
- **IBM**
- **IDT**
- **Infineon**
- **Intel**
- **LSI**
- **Marvell**
- **Maxim Integrated Products**
- **National Semiconductor**
- **NVIDIA**
- **NXP Semiconductors**
- **ON Semiconductor**
- **Oracle**
- **PMC-Sierra**
- **Qualcomm**
- **Samsung Electronics**
- **ST Microelectronics**
- **Texas Instruments**
- **VIA Technologies**
- **Xilinx**
Market Leader Sponsorship
(limited to 2 sponsors)

Marketing
• Logo on website identified as the Market Leader Sponsor
• 10,000 Leaderboard Banner Impressions Per Month
• Spotlight On Position with 3 links (above the fold, left hand column)
• Platinum Sponsor of one newsletter a month (486x60 banner +75 word text ad) sent out during your buy
• Add your blog to the Chip Design Featured Blog List

Lead Generation
• Up to 3 lead generation enabled white papers
• Dedicated quarterly email blast to community subscriber list (25,000)

Expanded Editorial Coverage
• Participation in content ticker below top navigation (your news headlines, article headlines, white paper headlines, viewpoint headlines, data sheet headlines run across content ticker)
• Unlimited Product Announcements
• Up to 3 videos featured on website
• One interview with Editor published on website and featured in email newsletter

Price: $6,500 per month (6 month minimum)

Platinum Sponsorship
(limited to 6 sponsors)

Marketing
• Logo on website identified as the Platinum Sponsor
• 10,000 Large Rectangle Banner Impressions Per Month
• Gold Sponsor of one Email Newsletter (120x600 skyscraper banner +75 word text ad)
• Add your blog to the Chip Design Featured Blog List

Lead Generation
• Up to 2 lead generation enabled white papers
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• Unlimited Product Announcements (we can use your RSS feeds)
• Up to 2 videos featured on website

Price: $3,500 per month (6 month minimum)

Website Marketing – Target the Chip Design Community

Exclusive “Spotlight On” Position
High impact and above the fold, this position leverages your headlines to drive maximum visibility and traffic to your site
Price - $4,500 per month (6 month minimum)

Exclusive Expandable Banner Showcase
High impact, center column position showcases your company as a market leader
Price - $3,500 per month (3 month minimum)

Banners
• Skyscraper (125x600) - $130 cpm
• Leaderboard (728x90) - $130 cpm
• Large Rectangle (336x280) - $130 cpm
• Banner Tiles (125x125) - $40 cpm
• Standard Pop-Under (336x280) - $350 cpm appears when browser closes
• Large Pop-Under (720x300) - $450 cpm appears when browser closes

Featured Videos/Blog
Each video or Blog is featured on ChipDesignMag.com and on ECatalog.com
• One video, 6 months - $1,500
• One video, 12 months - $2,000

PR Maximizer (New)
Unlimited PR; 2 online datasheets/product briefs; rotating 125x125 banner
$850 or $95 per month (6 month minimum; automatic renewal)
Add on: One Print Product Showcase ($1,500 total)

High Quality Targeted Lead Generation Programs Deliver for Your Sales Team!

White Paper Lead Generation Program
Submit your White Papers in PDF format and generate leads from the Chip Design market with these promos:
• Featured for 6 months on www.chipdesignmag.com and www.ecatalog.com
• Featured in Chip Designer and IP Designer & Integrator email newsletters that are broadcast monthly
• Showcased in 6 monthly Chip Design White Paper broadcasts
• $1500 per White Paper - OR - $3000 for 3 White Papers
• Dedicated email blast to 20,000 readers promoting your White Paper(s) for $2500.

Dedicated Email Blast
Send your own email blast to Chip Design subscriber lists
• $300 cpm (15,000 minimum list size)

Market Research and Lead Generation Program
These programs enable sponsors to gain valuable market intelligence and generate leads with detailed demographics. Sponsor provides up to 15 questions. We provide a 4 page executive summary report, contact information on survey respondents.
• 80 guaranteed responses/leads. - $7,500

White Paper Editorial Development
• Our Editors will write your White Paper - $7,500

Events: 8th Annual Multicore Developers Conference
The Only Combined Conference, Exhibition and Media Program Dedicated to the Deployment of Multicore and Virtualization Technology
• Two-day event with vetted presentations
• Before-During-After Marketing Impact
• Directed by Industry Leading Analysts
• Free Admittance to Qualified Registrants

Contact Sales Team for a Media Kit

Market Leader Sponsorship
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• Logo on website identified as the Market Leader Sponsor
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每月发布，IP Designer – Integrator e-Newsletter 提供知识产权（IP）设计和集成的最新资讯，包括芯片行业中的热点话题，如模拟、内存、设计、验证和IP集成和资格化在SoC空间。

**RF & Microwave Systems e-newsletter**
Trends, viewpoints, news and technical articles for design engineers and managers developing advanced RF and Microwave Systems designs

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Make sure you participate in the following 2012 Interoperability Guides:
- Spring (Foundry Ecosystems)
- Fall (IP Interoperability)
- Winter (Mentor Graphics)

Sponsor or participate in:
- **RF & Microwave Systems Special Issue** (May release)
- **Focus On: Design for Yield** (July release)

**Don’t be left out of these important 2013 Annual Engineers’ Guide Integrated Marketing Programs**
Distributed in print, online and email newsletter formats each Resource Catalog is designed to help over 70,000 well-qualified engineers, embedded developers and chip designers make effective design and purchasing decisions all year long.

**Custom Research and Lead Generation Program**
Gain valuable market intelligence and generate leads with detailed demographics. Sponsor provides up to 15 questions. We provide a 4 page executive summary report, contact information on survey respondents. 125 guaranteed respondents. $9,500

**Options**
- **Exclusive Roadblock-- Limited to one Sponsor**
  - 468x60 banner at top center position; side banner
  - 125 x up to 726; up to three text ads; - $6,000/issue
- **Platinum Sponsor**
  - 468x60 banner at top center position and first text ad - $2,500/issue
- **Gold Sponsor**
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- **Silver Sponsor**
  - Second from top 125x125 banner position and third text ad - $1,500/issue

**Sponsor Benefits/Opportunities Include:**
- Participation in creating survey questions
- Executive Summary and Analysis
- All research data

Sponsor Fee: $5,000

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2013 Editorial Calendar

Editorial Leadership

John Blyler, Editorial Director

He has worked in the electronics industry for over 25 years. Aside from editorial experience with the IEEE and technical trade journals, he has also co-authored books on systems-level design (IEEE-Wiley) and RF Design (Elsevier). John remains an affiliate professor in Systems Engineering at Portland State University.

Ed Spering, Consulting Editor

Ed is the Editor-in-Chief of the System-Level Design portal. He is the former Editor-in-Chief of Electronic News and Electronic Business.

Mark LaPedus, Senior Editor

Mark has covered the semiconductor industry since 1986. He has held senior editorial positions at EE Times, Silicon Strategies, Electronic News and EBN. In Asia, he was a contributing writer for Byte Magazine.

Cheryl Berglund Coupé, EECatalog.com Editor

Cheryl is editor of EECatalog.com and Embedded Intel® Solutions magazine. Cheryl’s articles have appeared in EE Times, Electronic Business, Microsoft Embedded Review and Windows Developer’s Journal and others.

Jenn Burkhardt, Managing Editor

Jenn is the managing editor for Chip Design, IP Designer and Chip Design magazine.

Pallab Chatterjee, Regional Editor

Pallab is an long-time consultant, analyst and writer in the EDA, Mixed Signal and custom design space. He is president of Silicon Map.

Dave Bursky, Senior Editor,

Dave is the former Editor-in-Chief of Penton’s Electronic Design and editor at EETimes.

Cheryl Ajluni, Contributing Editor

Cheryl is the former Editor-in-Chief for Wireless Systems Design. She is a patent-holding engineer with over 12 years experience covering the high-tech industry.

Ann Steffora Mutschler, Contributing Editor

Ann has been a semiconductor editor and journalist for nearly two decades. Previously, she was a senior editor EDN, Electronic News and Electronic Business.

Editorial Board

Cheryl Ajluni, Consultant, Custom Media Solutions
Karen Bartleson, Stds Manager, Synopsys
Chuck Byers, Director Communications, TSMC
Kathryn Kranen, CEO, Jasper Design Automation
Tom Moxon, Consultant, Moxon Design
Scott Sandler, CEO, Novas Software
Steve Schutz, President, Si2
Adam Traidman, Group Marketing Director, Chip Planning Solutions, Cadence Design Systems

2013 Chip Design Editorial Calendar

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<th>Focus Report/Insert</th>
<th>Key Editorial Topics</th>
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<td>HW-SW CoDesign • Low Power</td>
<td>DesignCon</td>
<td>Jan. 10 Jan. 14</td>
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<td>• DFM/DFY • SoC Design</td>
<td>• ASIC Proto - FPGA • Verification • Testing/Debug</td>
<td>ARM TechCon • SoC Conference</td>
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<td>RF &amp; Microwave Systems - IMS 2013 Special Issue</td>
<td>• Analog • RF and Wireless EDA Design Issues</td>
<td>Manufacturing Challenges • Multi-die packaging</td>
<td>International Microwave Symposium</td>
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<td>Focus On: Design for Yield</td>
<td>• Manufacturing issues for the Latest Nodes • DFM-DFY</td>
<td>• IP Integration • MEMS</td>
<td>Semicron West</td>
<td>June 17 June 20</td>
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Custom Content Marketing Solutions and Reprints from Chip Design

Hire the Chip Design Editorial and Marketing teams to produce and deliver valuable, relevant and compelling content for your customers and prospects on a consistent basis. Content marketing positions you as a trusted expert, impacts buying decisions, generates leads and improves SEO results! All custom content may also be featured on www.chipdesignmag.com.

Articles or Case Study (2 to 4 pages)
• 4 page: $7,500
• 2 page: $4,500

Branded Email Newsletters
Sent to combined list of your list and appropriate EECatalog subscribers (up to 40,000) and incorporating a featured article

White Papers (8 to 10 pages) - $9,500
Custom Blog
To appear on your website - will present brief chunks of valuable technology information and viewpoints related to your position in the market
• Monthly: $2,000 per month
• Weekly: $6,000 per month

Digital Magazines, print magazines, microsites, ebooks, social media add-ons quoted upon request

Reprints: Turn Chip Design print or online content into a powerful marketing piece and testimonial (print and online options)
• Quote provided upon request

Feature in Editorial Video (less than 10 minutes)
$3,000 (does not include travel if required)
### Chip Design Email Newsletter Editorial Calendar

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<th>Issue</th>
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<td>FPGA-Board</td>
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<td>Multicore Issues</td>
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<tr>
<td>April</td>
<td>IP Integration</td>
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<td>Interconnect</td>
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<td>Analog-Wireless</td>
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### IP Designer & Integrator newsletter

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<th>Issue</th>
<th>Feature Topic</th>
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<td>IP Trends</td>
<td>Jan 16</td>
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<tr>
<td>February</td>
<td>Core IP</td>
<td>Feb 13</td>
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### FPGA & CPLD Quarterly Update Newsletter

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<td>Q2</td>
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### RF & Microwave Systems

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<td>Feb 26</td>
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<td>Q2</td>
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### 2013 Annual Engineers' Guide Editorial Calendar

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<th>Market Focus</th>
<th>Pub Date</th>
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<tr>
<td>Low Power System Design</td>
<td>March</td>
<td>March 5</td>
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<td>Designers and engineers working on low power and power efficient designs</td>
<td>Design West</td>
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<td>Multicore and VirtualizationTechnologies</td>
<td>May 29</td>
<td>May 2</td>
<td>Designers and engineers using multicore and multiprocessing designs</td>
<td>Design West, Multicore DevCon</td>
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<tr>
<td>Enginee's Guide to Sensors and MEMS Design</td>
<td>May 10</td>
<td>May 14</td>
<td>Designers and engineers working with embedded sensors, MEMS and related technologies</td>
<td>Sensor Expo</td>
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<td>Chip Design Engineers' Guide</td>
<td>June 15</td>
<td>May 15</td>
<td>Advanced IC designers</td>
<td>DAC</td>
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<td>PCI Express</td>
<td>October</td>
<td>October 10</td>
<td>October 15</td>
<td>Engineers and embedded developers using or considering PCI Express solutions</td>
<td>DesignCon</td>
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<td>FPGA and PLD Solutions</td>
<td>November</td>
<td>November 26</td>
<td>November 30</td>
<td>FPGA and PLD system application engineers</td>
<td>DesignCon, DAC</td>
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